



Material Content Data Sheet



Sales Product Name		ISO1I813T		Issued		25. September 2017		
MA#		MA001031792						
Package		PG-TSSOP-48-2		Weight*		203.09 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	9.257	4.56	4.56	45582	45582
leadframe	inorganic material	phosphorus	7723-14-0	0.019	0.01		94	
	non noble metal	zinc	7440-66-6	0.076	0.04		375	
	non noble metal	iron	7439-89-6	1.524	0.75		7506	
wire	non noble metal	copper	7440-50-8	61.896	30.48	31.28	304769	312744
	noble metal	gold	7440-57-5	0.482	0.24	0.24	2373	2373
encapsulation	organic material	carbon black	1333-86-4	0.618	0.30		3041	
	plastics	epoxy resin	-	19.143	9.43		94257	
	inorganic material	silicondioxide	60676-86-0	103.742	51.07	60.80	510813	608111
leadfinish	non noble metal	tin	7440-31-5	2.496	1.23	1.23	12289	12289
plating	noble metal	silver	7440-22-4	0.774	0.38	0.38	3812	3812
glue	plastics	epoxy resin	-	0.766	0.38		3772	
	noble metal	silver	7440-22-4	2.298	1.13	1.51	11317	15089
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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